

MATECH

WaveEtch™ breakthrough thinning performance!

Matech™ Thinning Systems Deliver Unprecedented Performance! In response to the industry's latest requirements, the WaveEtch™ systems jump ahead of the competition and can now thin 6 inch substrates down to 50µm with a total thickness variation (TTV) of less than 2%! This is two to five times better than conventional systems.

Its patented *Linear Scan* and *Dynamic Confinement* technologies allow uniform etching at high rates on large area substrates.

The WaveEtch™ state-of-the-art robotics handle thin substrates automatically, out of their cassettes, throughout the whole process, and back, gently and efficiently. Precise and accurate dry-in dry-out thinning down to 50µm or less is now possible and cost effective.

Best of all, the WaveEtch™ systems offer this advanced thinning capability in a package that is affordable and has a lower cost of ownership. By using a small fraction of the chemicals used by similar spin or spray etching processes, the WaveEtch™ is also environmentally friendly.

Contact Matech™ for more information!

Go Ahead...

triple check your measurements!
WaveEtch™ performance is unparalleled

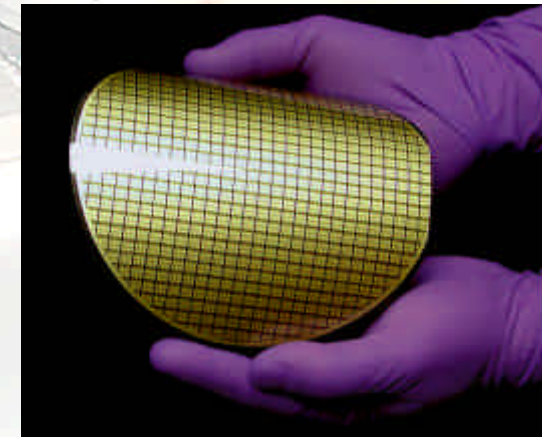


Image of a 6" wafer thinned to 50µm with the WaveEtch™ Linear Scan technology.

